

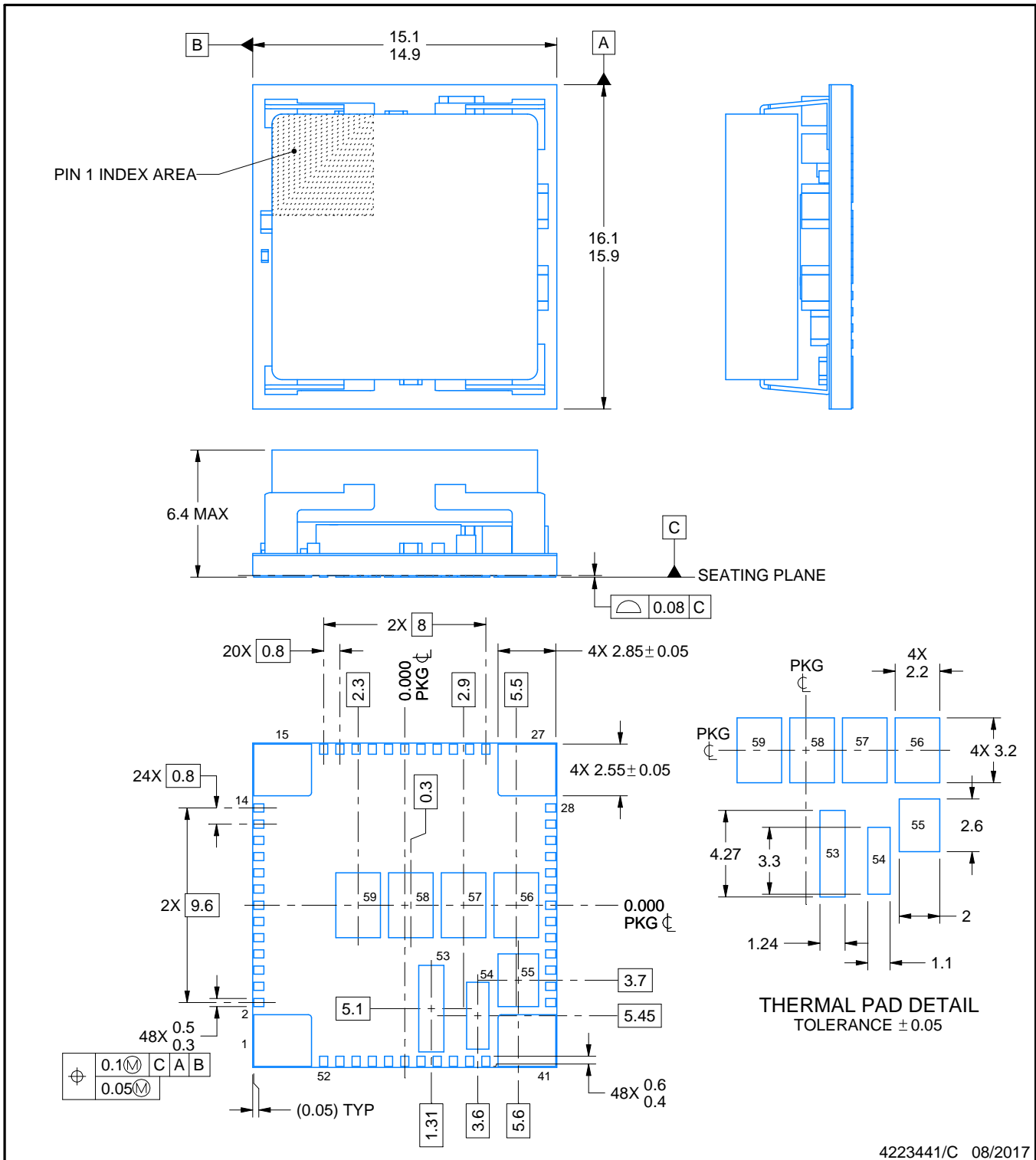
# MOL0059A



# PACKAGE OUTLINE

QFM - 6.4 mm max height

PLASTIC QUAD FLAT MODULE



**NOTES:**

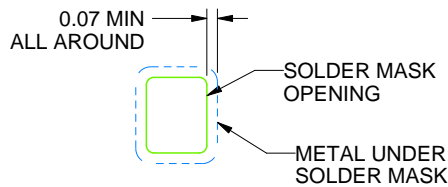
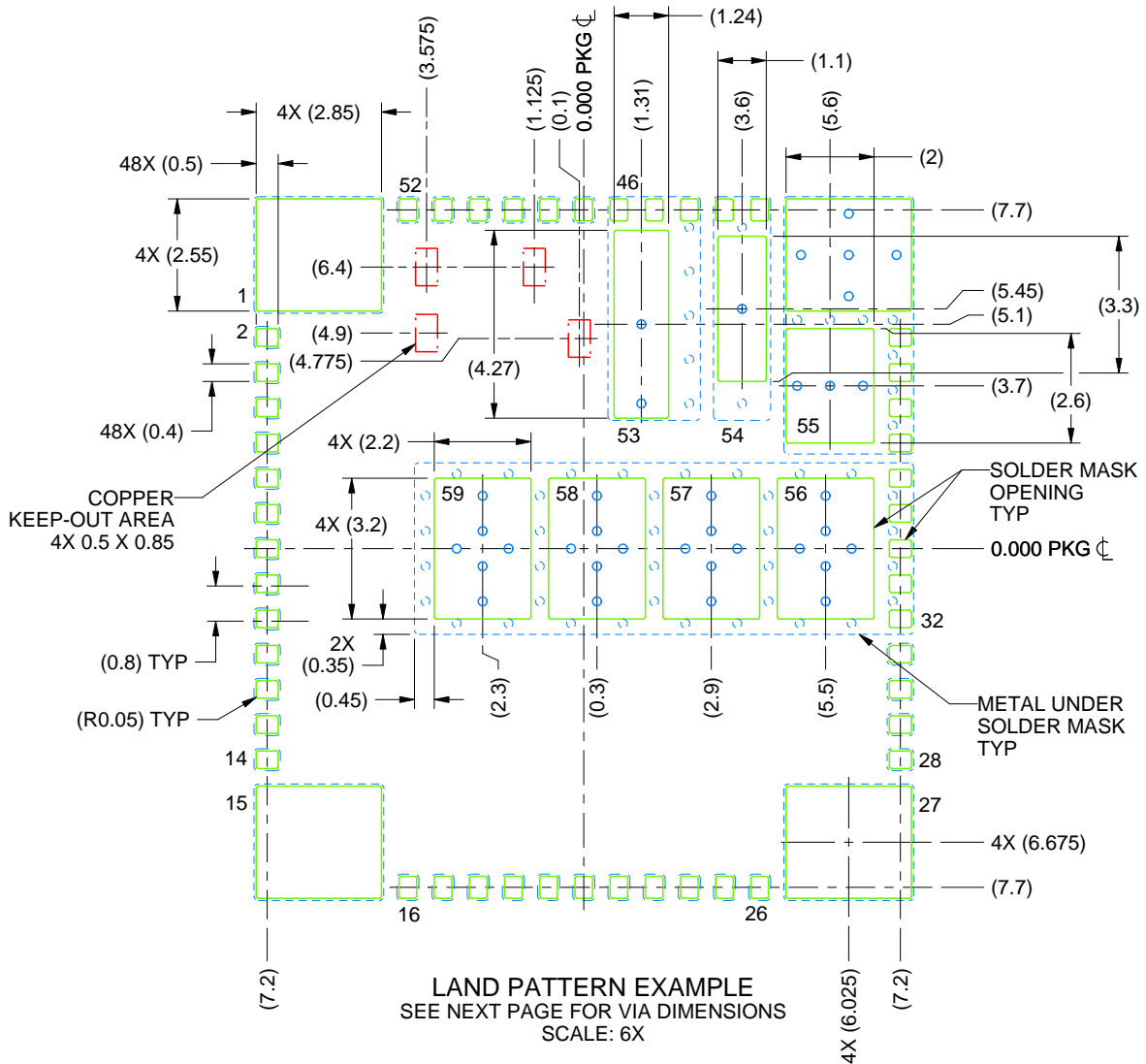
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pads must be soldered to the printed circuit board for optimal thermal and mechanical performance.

# EXAMPLE BOARD LAYOUT

MOL0059A

QFM - 6.4 mm max height

PLASTIC QUAD FLAT MODULE



SOLDER MASK DETAILS  
SOLDER MASK DEFINED PADS

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NOTES: (continued)

4. This package is designed to be soldered to the thermal pads on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/sluea271](http://www.ti.com/lit/sluea271)).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.





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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
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